



SOT1033-1

plastic thermal enhanced very very thin quad flat package;
no leads; 56 terminals; resin based; body 11 x 5 x 0.7 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN56R
Package type industry code	HWQFN56R
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	1-12-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	0.7	0.8	mm
A ₂	package height	[tbd]	-	0.7	[tbd]	mm
n ₂	actual quantity of termination	-	-	56	-	

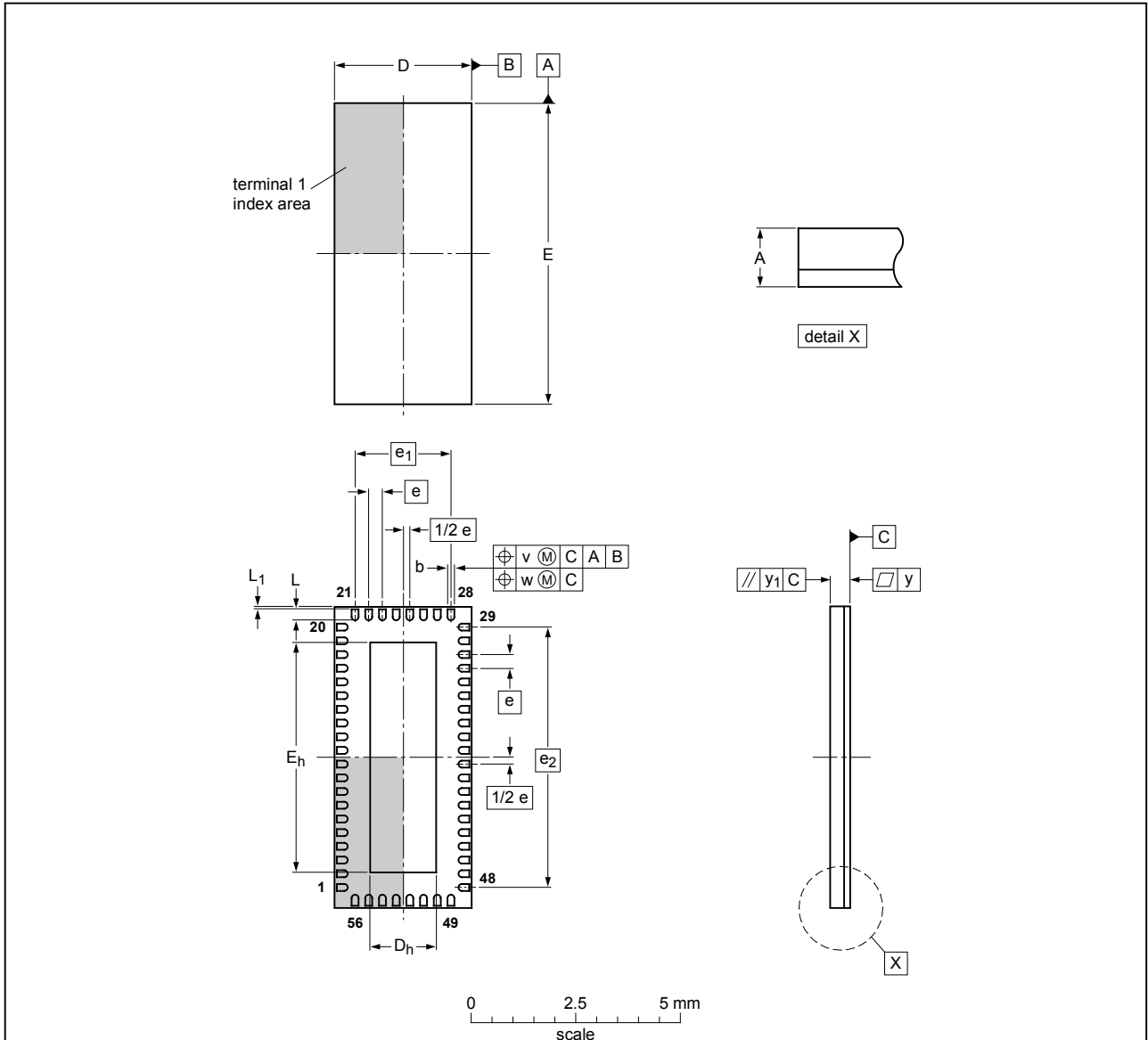


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2. Package outline

HWQFN56R: plastic thermal enhanced very very thin quad flat package; no leads; 56 terminals; resin based; body 11 x 5 x 0.7 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	0.8	0.27 0.23	5.1 4.9	2.5 2.3	11.1 10.9	8.5 8.3	0.5	3.5	9.5	0.42 0.38	0.1 0.0	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1033-1	---	---	---			07-09-19 07-12-01

Fig. 1. Package outline HWQFN56R (SOT1033-1)

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3. Legal information

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